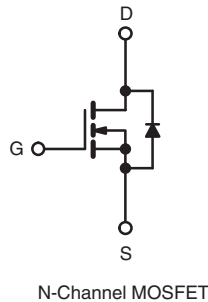
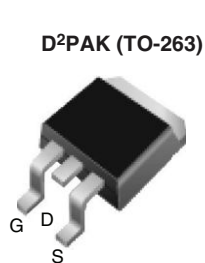


Power MOSFET

PRODUCT SUMMARY	
V_{DS} (V)	400
$R_{DS(on)}$ (Ω)	$V_{GS} = 10$ V 3.6
Q_g (Max.) (nC)	17
Q_{gs} (nC)	3.4
Q_{gd} (nC)	8.5
Configuration	Single



FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Surface Mount
- Available in Tape and Reel
- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC



RoHS*
COMPLIANT
HALOGEN
FREE
Available

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D²PAK (TO-263) is a surface mount power package capable of accommodating die size up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²PAK (TO-263) is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application.

ORDERING INFORMATION			
Package	D ² PAK (TO-263)	D ² PAK (TO-263)	D ² PAK (TO-263)
Lead (Pb)-free and Halogen-free	SiHF710S-GE3	SiHF710STRL-GE3 ^a	-
Lead (Pb)-free	IRF710SPbF	IRF710STRLPbF ^a	IRF710STRRPbF ^a
	SiHF710S-E3	SiHF710STL-E3 ^a	SiHF710STR-E3 ^a

Note

a. See device orientation.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	400	V	
Gate-Source Voltage		V_{GS}	± 20		
Continuous Drain Current	V_{GS} at 10 V	I_D	$T_C = 25$ °C	2.0	A
			$T_C = 100$ °C	1.2	
Pulsed Drain Current ^a		I_{DM}	6.0	W/°C	
Linear Derating Factor			0.29		
Linear Derating Factor (PCB Mount) ^e			0.025		
Single Pulse Avalanche Energy ^b		E_{AS}	120	mJ	
Avalanche Current ^a		I_{AR}	2.0	A	
Repetitive Avalanche Energy ^a		E_{AR}	3.6	mJ	
Maximum Power Dissipation	$T_C = 25$ °C	P_D	36	W	
	Maximum Power Dissipation (PCB Mount) ^e		$T_A = 25$ °C		3.1
Peak Diode Recovery dV/dt^c		dV/dt	4.0	V/ns	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature)	for 10 s		300 ^d		

Notes

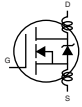
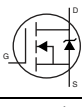
- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 52$ mH, $R_g = 25$ Ω , $I_{AS} = 2.0$ A (see fig. 12).
- $I_{SD} \leq 2.0$ A, $dI/dt \leq 40$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 150$ °C.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material).

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Maximum Junction-to-Ambient (PCB Mount) ^a	R_{thJA}	-	40	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.5	

Note

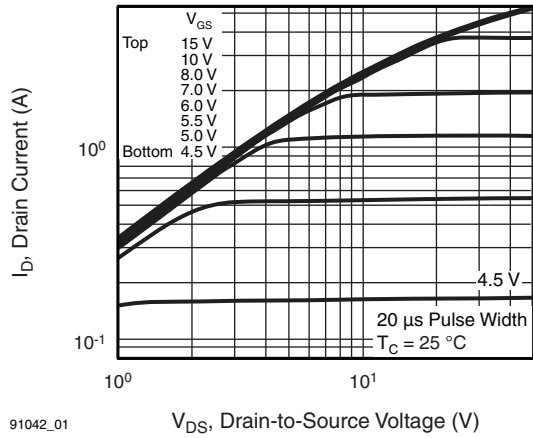
a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		400	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$		-	0.47	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		2.0	-	4.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20\text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}$		-	-	25	μA
		$V_{DS} = 320\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 1.2\text{ A}^b$	-	-	3.6	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 50\text{ V}, I_D = 1.2\text{ A}^b$		1.0	-	-	S
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$, see fig. 5		-	170	-	pF
Output Capacitance	C_{oss}			-	34	-	
Reverse Transfer Capacitance	C_{rss}			-	6.3	-	
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}$	$I_D = 2.0\text{ A}, V_{DS} = 320\text{ V}$, see fig. 6 and 13 ^b	-	-	17	nC
Gate-Source Charge	Q_{gs}			-	-	3.4	
Gate-Drain Charge	Q_{gd}			-	-	8.5	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 200\text{ V}, I_D = 2.0\text{ A}, R_g = 24\text{ }\Omega, R_D = 95\text{ }\Omega$, see fig. 10 ^b		-	8.0	-	ns
Rise Time	t_r			-	9.9	-	
Turn-Off Delay Time	$t_{d(off)}$			-	21	-	
Fall Time	t_f			-	11	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.5	-	nH
Internal Source Inductance	L_S			-	7.5	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	2.0	A
Pulsed Diode Forward Current ^a	I_{SM}			-	-	6.0	
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 2.0\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	1.6	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = 2.0\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$		-	240	540	ns
Body Diode Reverse Recovery Charge	Q_{rr}			-	0.85	1.6	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

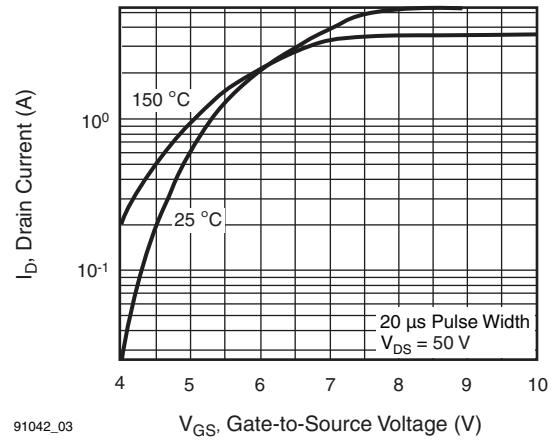
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



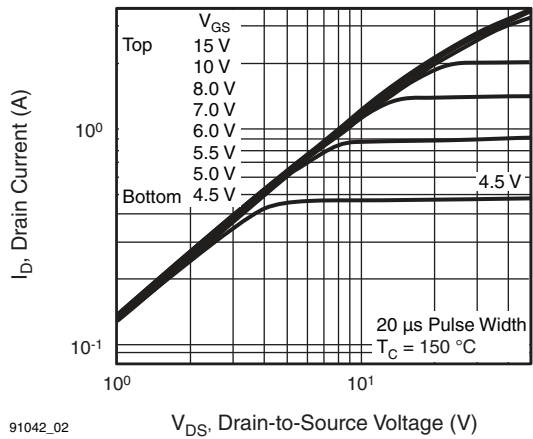
91042_01

Fig. 1 - Typical Output Characteristics, $T_C = 25\text{ °C}$



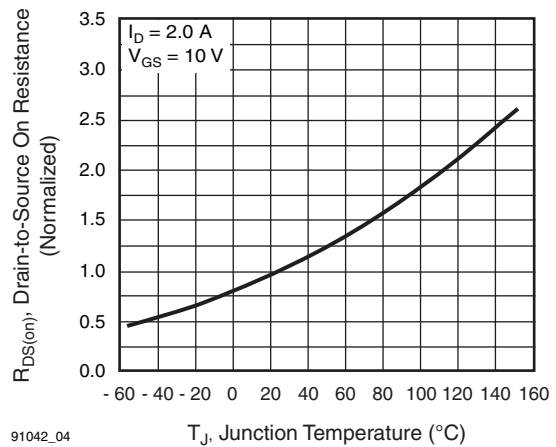
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Fig. 3 - Typical Transfer Characteristics



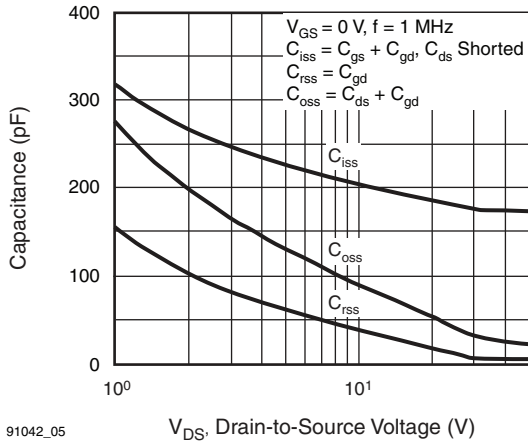
91042_02

Fig. 2 - Typical Output Characteristics, $T_C = 150\text{ °C}$



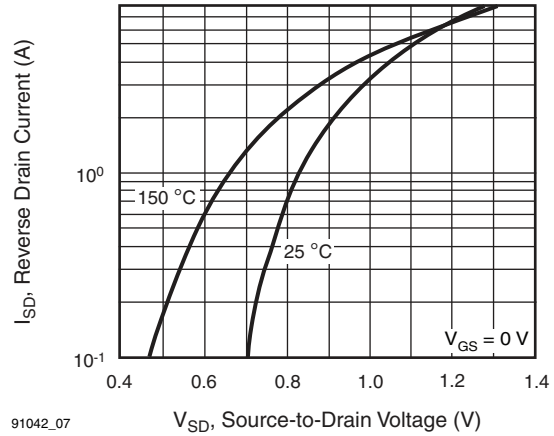
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Fig. 4 - Normalized On-Resistance vs. Temperature



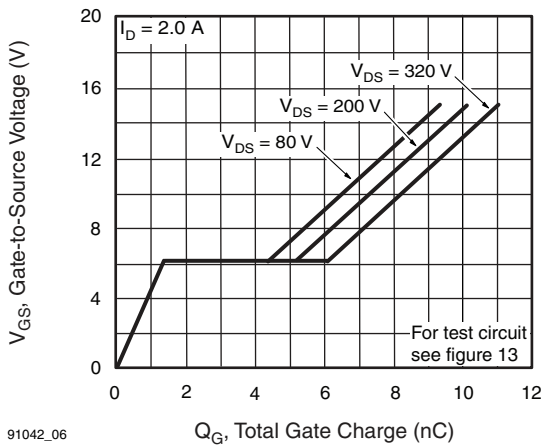
91042_05

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



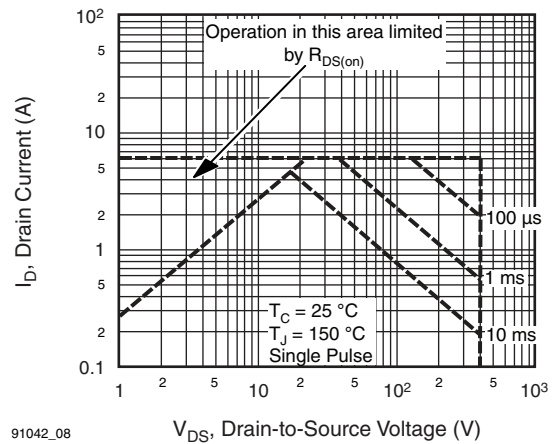
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Fig. 7 - Typical Source-Drain Diode Forward Voltage



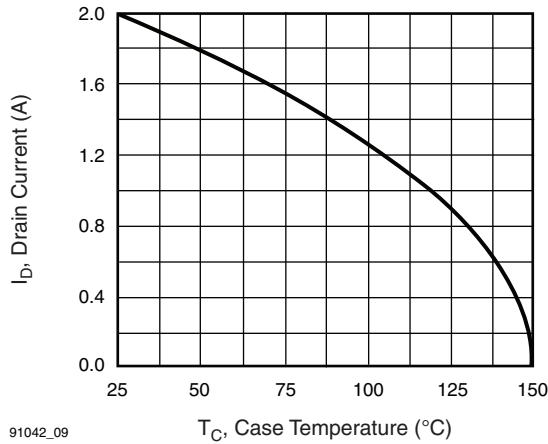
91042_06

Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



91042_08

Fig. 8 - Maximum Safe Operating Area



91042_09

Fig. 9 - Maximum Drain Current vs. Case Temperature

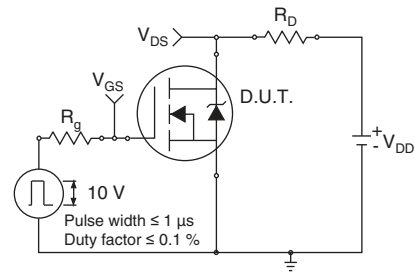
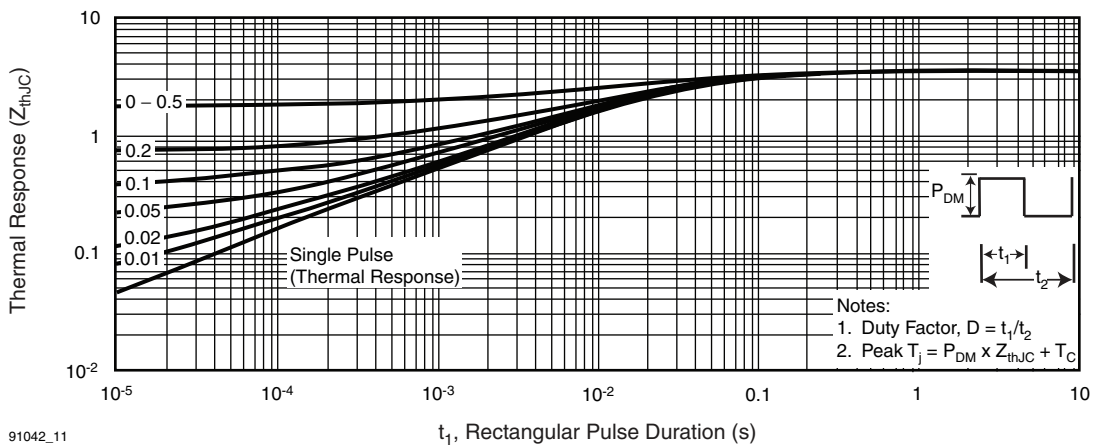


Fig. 10a - Switching Time Test Circuit



Fig. 10b - Switching Time Waveforms



91042_11

Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

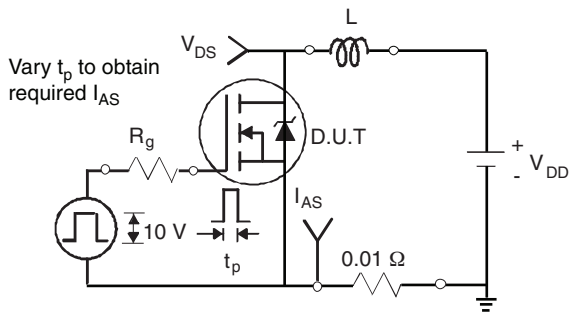


Fig. 12a - Unclamped Inductive Test Circuit

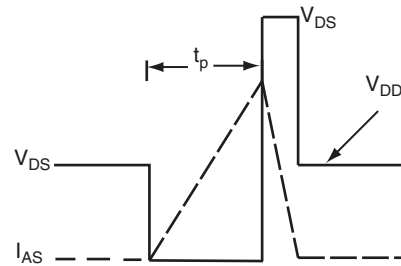
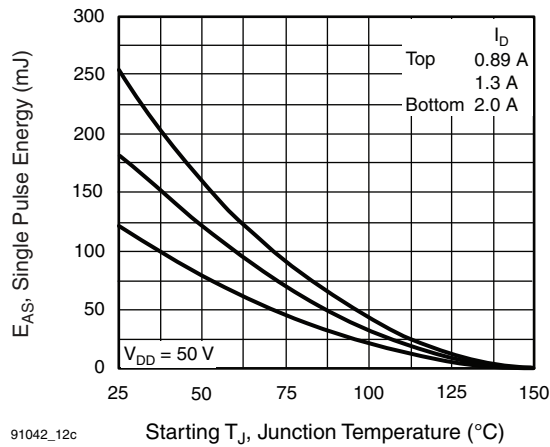


Fig. 12b - Unclamped Inductive Waveforms



91042_12c

Fig. 12c - Maximum Avalanche Energy vs. Drain Current

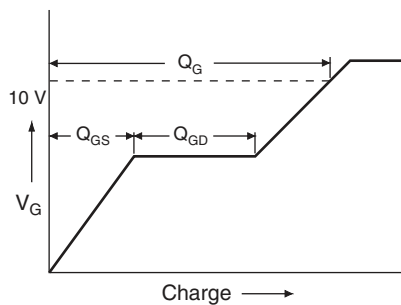


Fig. 13a - Basic Gate Charge Waveform

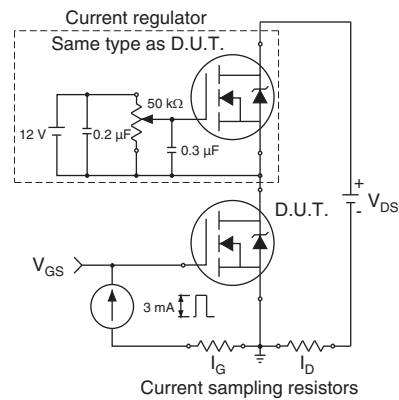
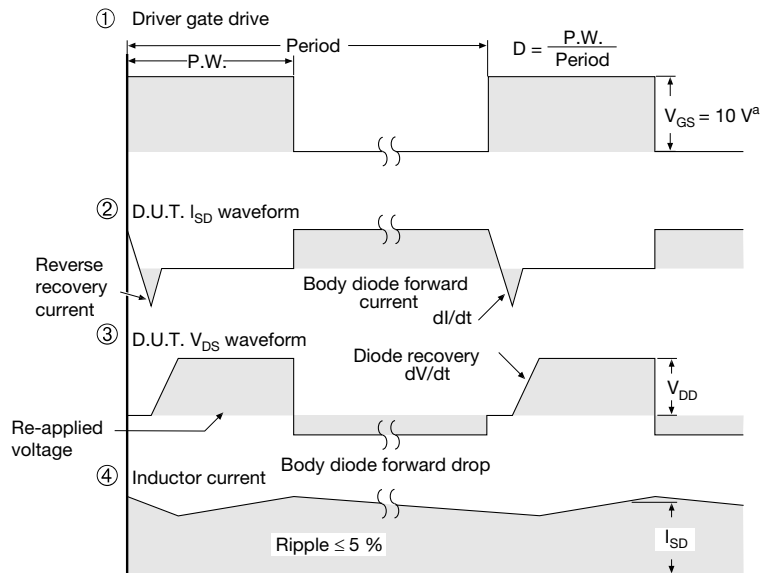
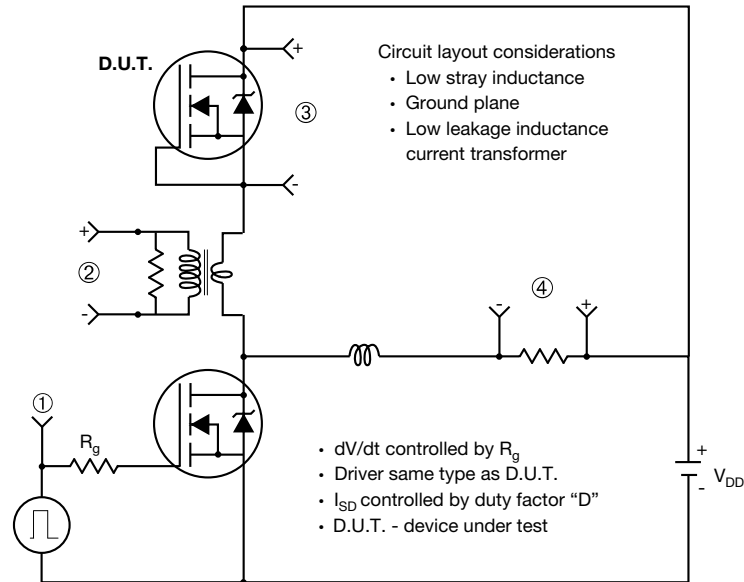


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel

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TO-263AB (HIGH VOLTAGE)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08
DWG: 5970

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

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Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.